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Abstract

In a process for the preparation of a flame-retardant, free-flowing, phenolically curable epoxy resin moulding material having latent reactivity for coating electronic components, a prepolymeric epoxy resin mixture free of isocyanate groups and having latent reactivity is prepared in powder form from a filler-containing thermally polymerisable reaction resin mixture of polyepoxy resin, comprising a mixture of di- and polyfunctional epoxy resins, and polyisocyanate resin having a molar ratio of epoxy groups to isocyanate groups of > 1 - using substituted imidazole as a reaction accelerator in a concentration of 0.5 to 2.5 %, based on polyepoxy resin - at reaction temperatures up to 200°C, and the prepolymeric epoxy resin mixture is mixed with a pulverulent, filler-containing phenol resin mixture in a molar ratio of epoxy groups to phenolic hydroxyl groups of 1:0.4 to 1:1.1, optionally with the addition of additives.

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